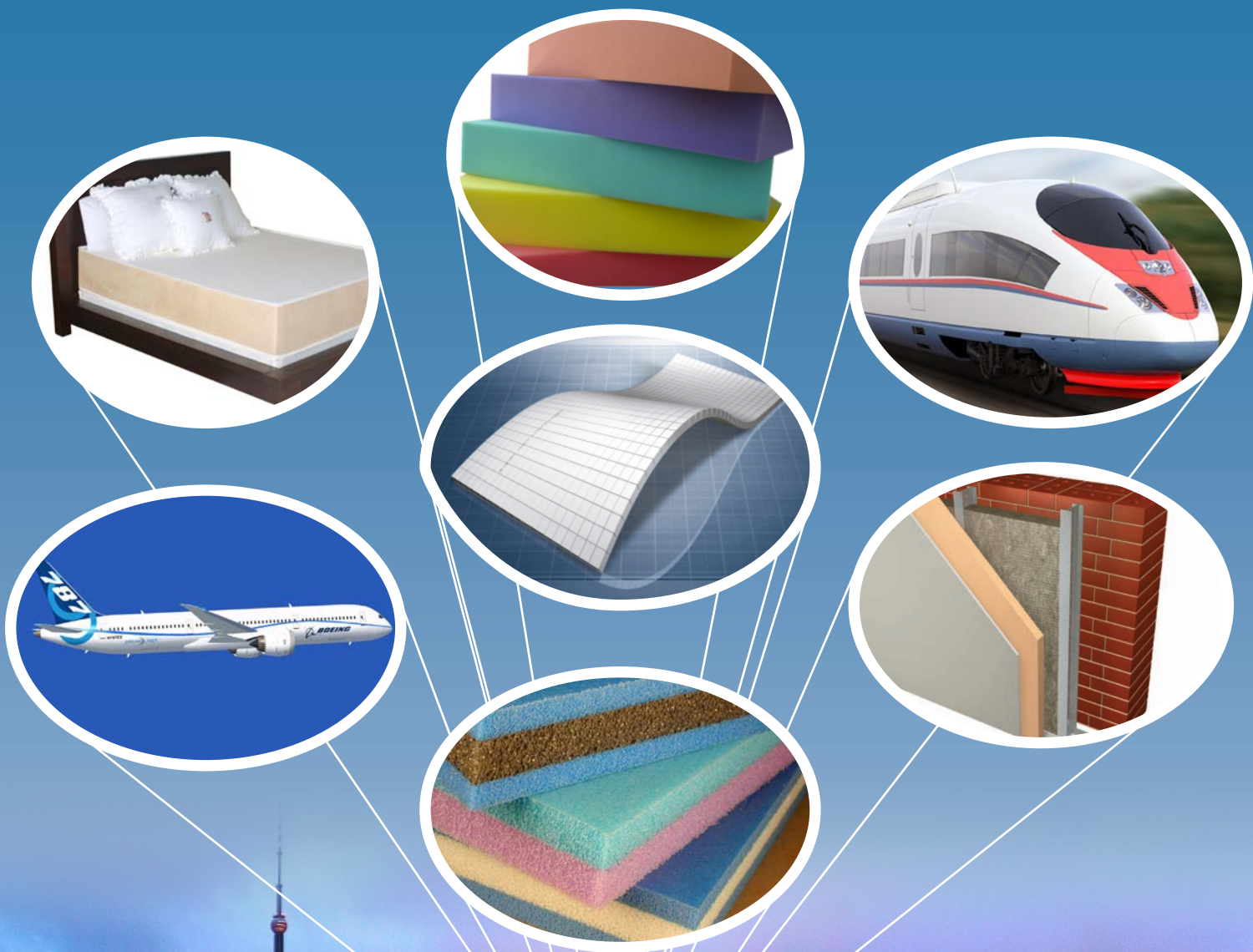


Poly-Foam 2014 Conference

Connection through Technology



Poly-Foam 2014 Conference

December 3-4, 2014 Shanghai, China

Foam Update is very pleased to announce the 2014 international Poly-Foam Conference to be held in Shanghai, China on December 3rd & 4th. Shanghai is a beautiful city of both mystery and momentum.

Innovation, technology, and application are the key elements for sustaining the success of foam globalization. Foam globalization has evolved from material conservation to meeting challenges of lightweighting to enhancing automotive mileage. It has improved degradation and recycling in the environment as well as high performance for unique applications to fully capture its inherent high surface area nature in foaming and in foamed products.

This conference offers a platform for effective connection and networking through presentation and exhibition. Social opportunities will provide insight on how technology can help generate new applications as well as innovation to further advance the global foam business.

EXHIBITION AND SUPPORT

Moldex3D, MuCell Extrusion, CCMCP,
Beijing Hu Long
Beijing University of Chemical Technology

SPONSOR THIS EVENT

A variety of sponsorship opportunities are available at this conference to help promote and enhance your company's products and services to this highly targeted international audience. Contact Foam Update at 201-221-6018 for more information.

TO GIVE THAN TO RECEIVE

This conference is hosted by Foam Update group
P. O. Box 906
Franklin Lakes, New Jersey, 07417 USA
tel: 201-221-6018

Wednesday 3rd December 2014

07:30 Registration and Welcome Coffee/Tea

08:30 Opening Announcement

SESSION 1 - BUSINESS

08:40 **Keynote Speech: Business Development Trends for Polymeric Foams**
Mr. Ken Chrisman; Vice President, Global Cushioning Products, Sealed Air Corporation

09:10 **Recent Technological and Application Development for Foamcore**
Mr. Tommo Tokiwa; Manager, JSP Corp.

09:40 **Thermal Dynamic Property of Rigid Foam Composites by DMA Techniques**
Dr. Ma, Wenguang; Director of R&D Center, TienSheng New Materials

10:10-10:40 Morning coffee/tea

SESSION 2 - FRIENDLY BLOWING AGENT

10:40 **The Dynamics History of Extruded Polystyrene Blowing Agents; from CFC, HCFC, HFC, Next?**
Dr. Yadi Delaviz; R&D Leader, Owens Corning

11:10 **The Role of DME on the Solubility of CO₂ in Polystyrene**
Prof. Xin, Chunling
Beijing University of Chemical Technology

11:40 **Formacel® 1100 (FEA-1100): A Zero ODP and Low GWP Foam Expansion Agent**
Li, Tony J-P.; Specialist, Du Pont

12:10-13:30 Lunch

SESSION 3 - MICROCELLULAR INJECTION MOLDING

13:30 **Enhancing Cell Nucleation for a Novel Microcellular Injection Molding Process**
Prof. Turng; L-S.; U. of Wisconsin-Madison

14:00 **Simulation and Experimental Investigation on Foaming Morphology of Microcellular Injection Molding Parts**
Dr. Huang, C-T.
Director of Technology, Moldex3D

14:30-15:00 afternoon coffee/tea

SESSION 4 - NOVEL PP FOAM TECHNOLOGY

- 15:00 **Expansible Polypropylene Development**
Mr. Lin, C-S.
Senior Manager, LCY Chemical Corp.
- 15:30 **Supercritical CO₂ Assisted Compression Foaming of Polypropylene**
Dr. Jiang, Xiulei; Xinhengtai New Materials
- 16:00 **Preparation and Foaming Application of High Melt Strength PP**
Dr. Guo, Peng; Sinopec
- 16:30 **Study on the Foaming Behavior with SC-CO₂ for a Series of HMS-PP with Various Structures and Its Melt Rheological Properties**
Prof. Kun Cao; Zhejiang University

17:00-19:00 Conference Cocktails

Thursday 4th December 2014

08:00 Registration and Welcome Coffee/Tea

SESSION 5 - MICROCELLULAR DEVELOPMENT

- 08:15 **Equipment and Material Considerations for Microcellular Foaming**
Mr. Mark Lindenfelzer
President, MuCell Extrusion
- 08:45 **High-Pressure CO₂ Aided New Processes for PET Foams Preparation**
Prof. Zhao, Ling
East China University of Technology
- 09:15 **Microcellular Foams of Poly (phenylene sulfide)/Poly(ether sulfones) (PPS/PES) Blends Generated by Supercritical Carbon Dioxide**
Mr. Ma, Zhonglei
Northwestern Polytechnical University

09:45-10:15 morning coffee/tea

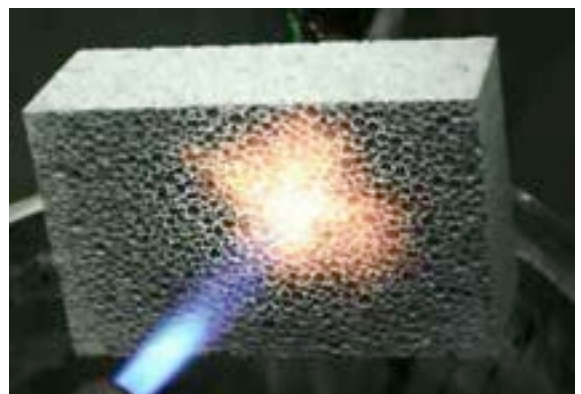
SESSION 6 - INNOVATION

- 10:15 **Decoupling the Effects of Cell and Foam Densities on the Electrical Conductivity and Percolation Threshold in Polymer Composite Foams**
Prof. Park, C. B.; University of Toronto

- 10:45 **Physical Properties and Anti-Termite of Extruded Polycarbonate Foam**
Mr. Tatsuyuki Ishikawa
Research Engineer, JSP Corp.
- 11:15 **Development of New Generation Flame Retardant XPS**
Mr. Sun, Yiming; Manager, Owens Corning
- 11:45 **Effect of Viscoelastic Property on Cellular Morphology of Silicone rubber generated by Supercritical CO₂**
Prof. Liao, Xia; Sichuan University
- 12:15-13:30 lunch

SESSION 7 - FUTURE

- 13:30 **Preparation and Cellular Structure of Microcellular PLA/PS Blend Foams**
Prof. Huang, Hanxiong
South China University of Technology
- 14:00 **Effects of Crystal Morphology of PP on Microcellular Structures of Batch Foamed PP and PP/ PBT Nanofiber Composites**
Prof. He, Yadong
Beijing University of Chemical Technology
- 14:30 **Fabrication of Polyetherimide Microcellular foam for EMI**
Dr. Zhai, Wentao
Chinese Academy of Science,
Ningbo Key Lab of Polymer materials
- 15:00 **Concluding Remarks; This Conference and Beyond; PP and PVC foam**
Dr. Lee, S. T.; Sr. Fellow, Sealed Air Corp.
- 15:15 **Conference Ends**



(courtesy of BASF)

Poly-Foam 2014 Conference

Registration Form

Name:

Title:

Company:

Address:

City/State/Country/Zip Code:

e-mail:

Phone:

Payment Method: in RMB or US\$

(Please circle one)

1. By check: mail to:
P.O. Box 906
Franklin Lakes, NJ, 07417
2. By Bank Transfer:
 - a. Bank Name: JP Morgan Chase
 - b. Address:
345 Ramapo Valley Road
Oakland, NJ 07436
 - c. Swift Code: CHASUS33
 - d. Account Name/number:
Foam Update/2928813357
3. By Credit Card:
Visa/Master Card/American Express

a. Cardholder Name:

b. Card Number:

c. Expiration Date:

d. Signature:

Please fax the completed form to 201-337-7283,
or e-mail to mjaulin@foamupdate.com, or mail
to:

P.O. Box 906

Franklin Lakes, New Jersey 07417

Conference Information

Date:

December 3-4, 2014

Location:

Shanghai JingAn Hilton
250 Hua-Shan Road
Shanghai, 200040, China

Registration Fee Chart*

(Advance cut-off date: July 31, 2014)

Please circle the amount:

Conference:

\$960 or RMB 5,950 (advance)

\$1,200 or RMB 7,440 (regular)

Exhibition:

\$1,800 or RMB 11,160 (advance)

\$2,000 or RMB 12,400 (regular)

(exhibition includes one delegate)

Please contact us for sponsoring breaks, lunch,
or cocktail

General Sponsor (logo in the program):

Academia = \$500 or RMB3,100

Industry = \$1,000 or RMB6,200

Venue:

Jing An Hilton Hotel, Group Code: GFOAA; RMB
950/day with breakfast good until Nov. 12, 2014

Visa:

China allows a 72-hour visa exemption for the
Shanghai district, please contact us for a support
letter to apply for the visa if your stay for this
conference is longer than 72 hours.

Local contact:

Mr. Zhang Wei at

86-13818723666 (M)

To Give than to Receive

This conference is hosted by Foam Update group
P. O. Box 906

Franklin Lakes, New Jersey, 07417 USA

tel: 201-221-6018

*group rate of five delegates and more is available
upon request

Receipt will be available upon request.